ABSTRACT OF THE DISCLOSURE

A method of making a moisture-proof package that holds semiconductor devices and desiccant is provided. A tray that retains desiccant is prepared. Semiconductor devices are placed on the tray, and the semiconductor devices and the desiccant carried by the tray are then heat treated before being sealed in a moisture-proof bag. Once the semiconductor devices are shipped to customers, the tray and desiccant are both reused until the moisture absorbing properties of the desiccant diminish.